



# PCF85063TP

## Tiny Real-Time Clock/calendar

Rev. 4 — 6 May 2015

Product data sheet

### 1. General description

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The PCF85063TP is a CMOS<sup>1</sup> Real-Time Clock (RTC) and calendar optimized for low power consumption. An offset register allows fine-tuning of the clock. All addresses and data are transferred serially via the two-line bidirectional I<sup>2</sup>C-bus. Maximum bus speed is 400 kbit/s. The register address is incremented automatically after each written or read data byte.

For a selection of NXP Real-Time Clocks, see [Table 35 on page 43](#)

### 2. Features and benefits

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- Provides year, month, day, weekday, hours, minutes, and seconds based on a 32.768 kHz quartz crystal
- Clock operating voltage: 0.9 V to 5.5 V
- Low current: typical 0.22  $\mu$ A at  $V_{DD} = 3.3$  V and  $T_{amb} = 25$  °C
- 400 kHz two-line I<sup>2</sup>C-bus interface (at  $V_{DD} = 1.8$  V to 5.5 V)
- Programmable clock output for peripheral devices (32.768 kHz, 16.384 kHz, 8.192 kHz, 4.096 kHz, 2.048 kHz, 1.024 kHz, and 1 Hz)
- Selectable integrated oscillator load capacitors for  $C_L = 7$  pF or  $C_L = 12.5$  pF
- Minute and half minute interrupt
- Oscillator stop detection function
- Internal Power-On Reset (POR)
- Programmable offset register for frequency adjustment

### 3. Applications

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- Digital still camera
- Digital video camera
- Printers
- Copy machines
- Mobile equipment
- Battery powered devices

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1. The definition of the abbreviations and acronyms used in this data sheet can be found in [Section 21](#).



## 4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
PCF85063TP	HWSON8	plastic thermal enhanced very very thin small outline package; no leads; 8 terminals; body 2 × 3 × 0.75 mm	SOT1069-2

### 4.1 Ordering options

Table 2. Ordering options

Product type number	Orderable part number	Sales item (12NC)	Delivery form	IC revision
PCF85063TP/1	PCF85063TP/1Z	935297365147	tape and reel, 7 inch	1

## 5. Marking

Table 3. Marking codes

Product type number	Marking code
PCF85063TP/1	063

## 6. Block diagram

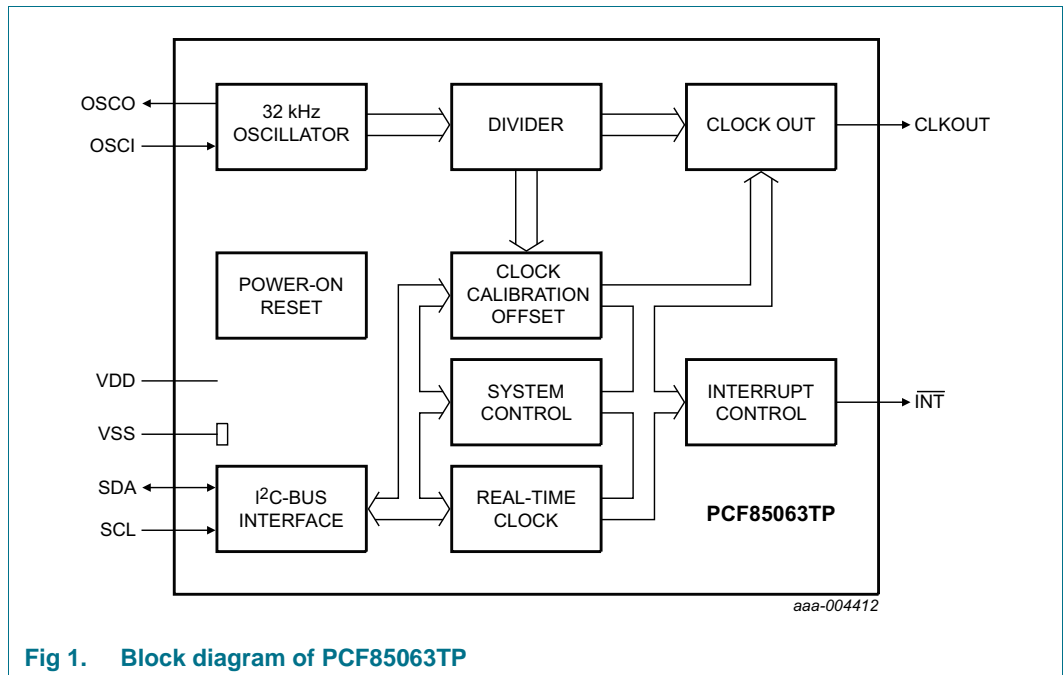
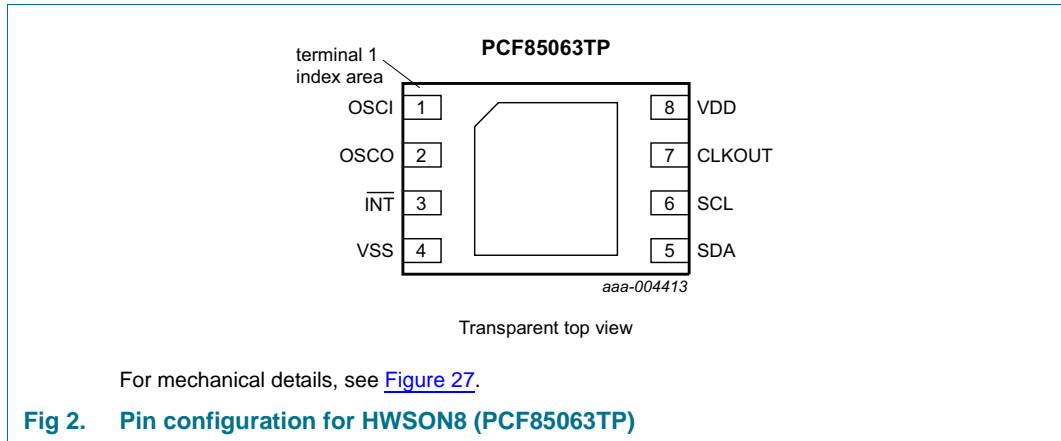


Fig 1. Block diagram of PCF85063TP

## 7. Pinning information

### 7.1 Pinning



### 7.2 Pin description

**Table 4. Pin description**

*Input or input/output pins must always be at a defined level ( $V_{SS}$  or  $V_{DD}$ ) unless otherwise specified.*

Symbol	Pin	Type	Description
OSCI	1	input	oscillator input
OSCO	2	output	oscillator output
INT	3	output	interrupt output (open-drain)
VSS	4 <sup>[1]</sup>	supply	ground supply voltage
SDA	5	input/output	serial data line
SCL	6	input	serial clock input
CLKOUT	7	output	clock output (push-pull)
VDD	8	supply	supply voltage

[1] The die paddle (exposed pad) is connected to  $V_{SS}$  and should be electrically isolated.

## 8. Functional description

The PCF85063TP contains 11 8-bit registers with an auto-incrementing register address, an on-chip 32.768 kHz oscillator with integrated capacitors, a frequency divider which provides the source clock for the Real-Time Clock (RTC) and calendar, and an I<sup>2</sup>C-bus interface with a maximum data rate of 400 kbit/s.

The built-in address register will increment automatically after each read or write of a data byte up to the register 0Ah. After register 0Ah, the auto-incrementing will wrap around to address 00h (see [Figure 3](#)).

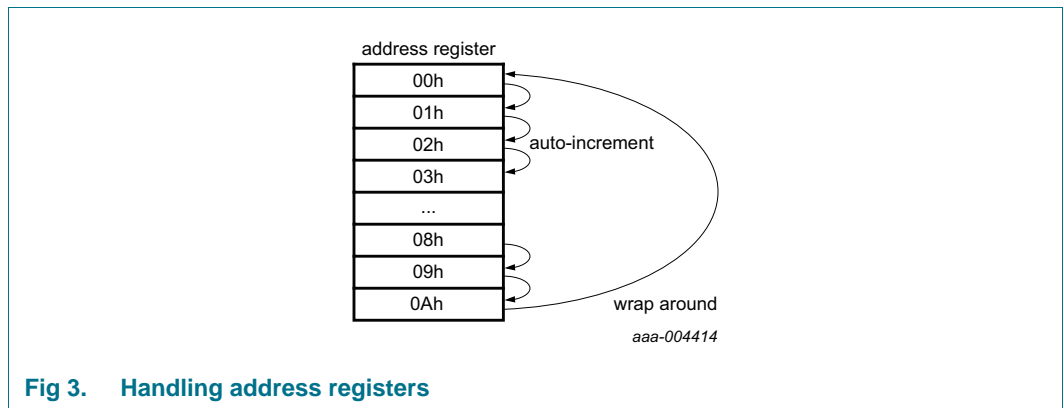


Fig 3. Handling address registers

All 11 registers (see [Table 5](#)) are designed as addressable 8-bit parallel registers although not all bits are implemented. The first two registers (memory address 00h and 01h) are used as control and status register. The register at address 02h is an offset register allowing the fine-tuning of the clock; and at 03h is a free RAM byte. The addresses 04h through 0Ah are used as counters for the clock function (seconds up to years counters).

The Seconds, Minutes, Hours, Days, Months, and Years registers are all coded in Binary Coded Decimal (BCD) format. When one of the RTC registers is written or read, the contents of all time counters are frozen. Therefore, faulty writing or reading of the clock and calendar during a carry condition is prevented.

## 8.1 Registers organization

**Table 5. Registers overview**

Bit positions labeled as - are not implemented. After reset, all registers are set according to [Table 8 on page 10](#).

Address	Register name	Bit								Reference	
		7	6	5	4	3	2	1	0		
<b>Control and status registers</b>											
00h	Control_1	EXT_TEST	-	STOP	SR	-	CIE	12_24	CAP_SEL	<a href="#">Section 8.2.1</a>	
01h	Control_2	-	-	MI	HMI	TF	COF[2:0]			<a href="#">Section 8.2.2</a>	
02h	Offset	MODE	OFFSET[6:0]								<a href="#">Section 8.2.3</a>
03h	RAM_byte	B[7:0]								<a href="#">Section 8.2.4</a>	
<b>Time and date registers</b>											
04h	Seconds	OS	SECONDS (0 to 59)								<a href="#">Section 8.3.1</a>
05h	Minutes	-	MINUTES (0 to 59)								<a href="#">Section 8.3.2</a>
06h	Hours	-	-	AMPM	HOURS (1 to 12) in 12 hour mode					<a href="#">Section 8.3.3</a>	
				HOURS (0 to 23) in 24 hour mode							
07h	Days	-	-	DAYS (1 to 31)						<a href="#">Section 8.3.4</a>	
08h	Weekdays	-	-	-	-	-	WEEKDAYS (0 to 6)				<a href="#">Section 8.3.5</a>
09h	Months	-	-	-	MONTHS (1 to 12)					<a href="#">Section 8.3.6</a>	
0Ah	Years	YEARS (0 to 99)									<a href="#">Section 8.3.7</a>

## 8.2 Control registers

### 8.2.1 Register Control\_1

Table 6. Control\_1 - control and status register 1 (address 00h) bit description

Bit	Symbol	Value	Description	Reference
7	EXT_TEST		<b>external clock test mode</b>	<a href="#">Section 8.2.1.1</a>
		0 <sup>[1]</sup>	normal mode	
		1	external clock test mode	
6	-	0	unused	-
5	STOP		<b>STOP bit</b>	<a href="#">Section 8.2.1.2</a>
		0 <sup>[1]</sup>	RTC clock runs	
		1	RTC clock is stopped; all RTC divider chain flip-flops are asynchronously set logic 0	
4	SR		<b>software reset</b>	<a href="#">Section 8.2.1.3</a>
		0 <sup>[1]</sup>	no software reset	
		1	initiate software reset <sup>[2]</sup> ; this bit always returns a 0 when read	
3	-	0	unused	-
2	CIE		<b>correction interrupt enable</b>	<a href="#">Section 8.2.3</a>
		0 <sup>[1]</sup>	no correction interrupt generated	
		1	interrupt pulses are generated at every correction cycle	
1	12_24		<b>12 or 24 hour mode</b>	<a href="#">Section 8.3.3</a>
		0 <sup>[1]</sup>	24 hour mode is selected	
		1	12 hour mode is selected	
0	CAP_SEL		<b>internal oscillator capacitor selection</b> for quartz crystals with a corresponding load capacitance	-
		0 <sup>[1]</sup>	7 pF	
		1	12.5 pF	

[1] Default value.

[2] For a software reset, 01011000 (58h) must be sent to register Control\_1 (see [Section 8.2.1.3](#)).

### 8.2.1.1 EXT\_TEST: external clock test mode

A test mode is available which allows for on-board testing. In this mode, it is possible to set up test conditions and control the operation of the RTC.

The test mode is entered by setting bit EXT\_TEST in register Control\_1. Then pin CLKOUT becomes an input. The test mode replaces the internal clock signal with the signal applied to pin CLKOUT.

The signal applied to pin CLKOUT should have a minimum pulse width of 300 ns and a maximum period of 1000 ns. The internal clock, now sourced from CLKOUT, is divided down to 1 Hz by a  $2^6$  divide chain called a prescaler. The prescaler can be set into a known state by using bit STOP. When bit STOP is set, the prescaler is reset to 0. (STOP must be cleared before the prescaler can operate again.)

From a stop condition, the first 1 second increment will take place after 32 positive edges on pin CLKOUT. Thereafter, every 64 positive edges cause a 1 second increment.

**Remark:** Entry into test mode is not synchronized to the internal 64 Hz clock. When entering the test mode, no assumption as to the state of the prescaler can be made.

Operation example:

1. Set EXT\_TEST test mode (register Control\_1, bit EXT\_TEST = 1)
2. Set STOP (register Control\_1, bit STOP = 1)
3. Clear STOP (register Control\_1, bit STOP = 0)
4. Set time registers to desired value
5. Apply 32 clock pulses to pin CLKOUT
6. Read time registers to see the first change
7. Apply 64 clock pulses to pin CLKOUT
8. Read time registers to see the second change

Repeat 7 and 8 for additional increments.

8.2.1.2 STOP: STOP bit function

The function of the STOP bit (see [Figure 4](#)) is to allow for accurate starting of the time circuits. The STOP bit function causes the upper part of the prescaler (F<sub>2</sub> to F<sub>14</sub>) to be held in reset and thus no 1 Hz ticks are generated. It also stops the output of clock frequencies lower than 8 kHz on pin CLKOUT.

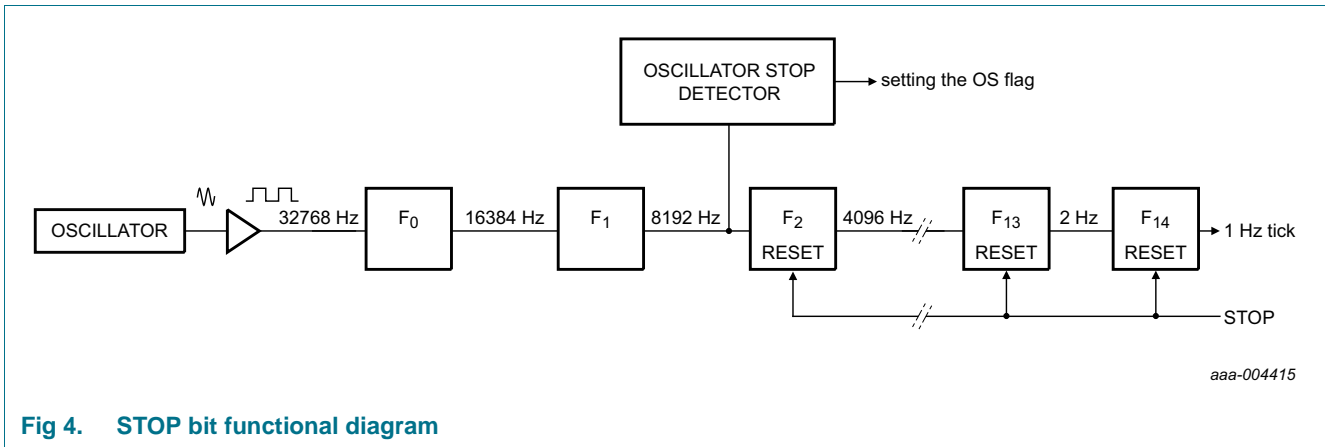


Fig 4. STOP bit functional diagram

The time circuits can then be set and do not increment until the STOP bit is released (see [Figure 5](#) and [Table 7](#)).



Table 7. First increment of time circuits after STOP bit release

Bit	Prescaler bits	[1] 1 Hz tick	Time	Comment	
STOP	F <sub>0</sub> F <sub>1</sub> -F <sub>2</sub> to F <sub>14</sub>		hh:mm:ss		
<b>Clock is running normally</b>					
0	01-0 0001 1101 0100		12:45:12	prescaler counting normally	
<b>STOP bit is activated by user. F<sub>0</sub>F<sub>1</sub> are not reset and values cannot be predicted externally</b>					
1	XX-0 0000 0000 0000		12:45:12	prescaler is reset; time circuits are frozen	
<b>New time is set by user</b>					
1	XX-0 0000 0000 0000		08:00:00	prescaler is reset; time circuits are frozen	
<b>STOP bit is released by user</b>					
0	XX-0 0000 0000 0000		08:00:00	prescaler is now running	
	XX-1 0000 0000 0000		08:00:00	-	
	XX-0 1000 0000 0000		08:00:00	-	
	XX-1 1000 0000 0000		08:00:00	-	
	:		:	:	-
	11-1 1111 1111 1110		08:00:00	-	
	00-0 0000 0000 0001		08:00:01	0 to 1 transition of F <sub>14</sub> increments the time circuits	
	10-0 0000 0000 0001		08:00:01	-	
	:		:	:	-
	11-1 1111 1111 1111		08:00:01	-	
	00-0 0000 0000 0000		08:00:01	-	
	10-0 0000 0000 0000		08:00:01	-	
	:		:	:	-
	11-1 1111 1111 1110		08:00:01	-	
	00-0 0000 0000 0001		08:00:02	0 to 1 transition of F <sub>14</sub> increments the time circuits	

[1] F<sub>0</sub> is clocked at 32.768 kHz.

The lower two stages of the prescaler (F<sub>0</sub> and F<sub>1</sub>) are not reset. And because the I<sup>2</sup>C-bus is asynchronous to the crystal oscillator, the accuracy of restarting the time circuits is between zero and one 8.192 kHz cycle (see Figure 5).

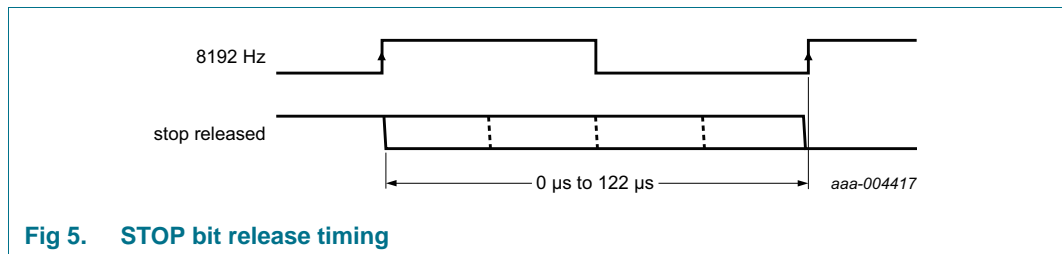


Fig 5. STOP bit release timing

The first increment of the time circuits is between 0.507813 s and 0.507935 s after STOP bit is released. The uncertainty is caused by the prescaler bits F<sub>0</sub> and F<sub>1</sub> not being reset (see Table 7) and the unknown state of the 32 kHz clock.

8.2.1.3 Software reset

A reset is automatically generated at power-on. A reset can also be initiated with the software reset command. Software reset command means setting bits 6, 4, and 3 in register Control\_1 (00h) logic 1 and all other bits logic 0 by sending the bit sequence 01011000 (58h), see [Figure 6](#).

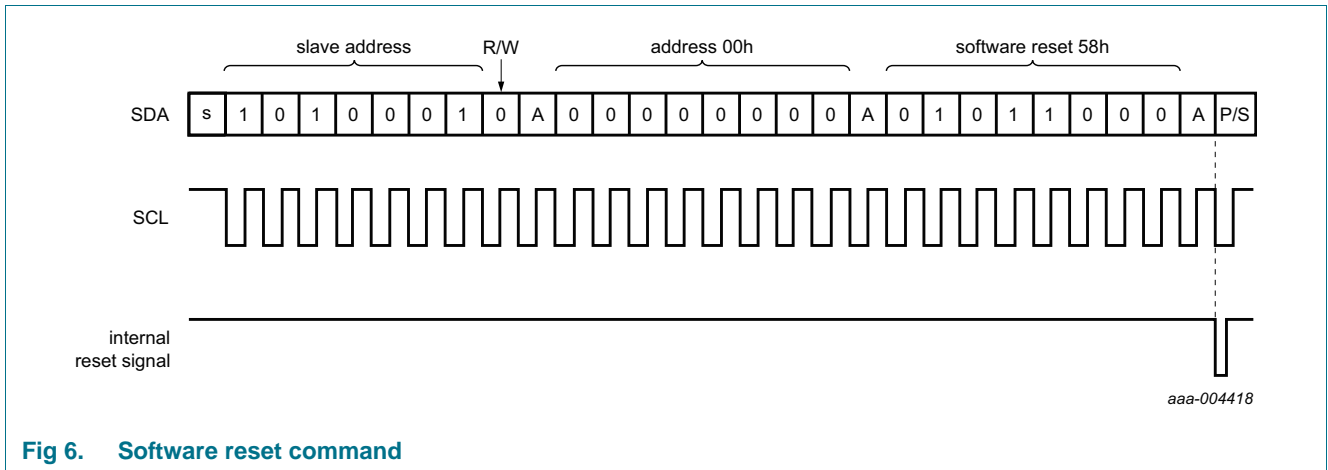


Fig 6. Software reset command

In reset state all registers are set according to [Table 8](#) and the address pointer returns to address 00h.

Table 8. Register reset values

Address	Register name	Bit							
		7	6	5	4	3	2	1	0
00h	Control_1	0	0	0	0	0	0	0	0
01h	Control_2	0	0	0	0	0	0	0	0
02h	Offset	0	0	0	0	0	0	0	0
03h	RAM_byte	0	0	0	0	0	0	0	0
04h	Seconds	1	0	0	0	0	0	0	0
05h	Minutes	0	0	0	0	0	0	0	0
06h	Hours	0	0	0	0	0	0	0	0
07h	Days	0	0	0	0	0	0	0	1
08h	Weekdays	0	0	0	0	0	1	1	0
09h	Months	0	0	0	0	0	0	0	1
0Ah	Years	0	0	0	0	0	0	0	0

The PCF85063TP resets to:

**Time** — 00:00:00

**Date** — 20000101

**Weekday** — Saturday

8.2.2 Register Control\_2

Table 9. Control\_2 - control and status register 2 (address 01h) bit description

Bit	Symbol	Value	Description
7 to 6	-	00	unused
5	MI		<b>minute interrupt</b>
		0 <sup>[1]</sup>	disabled
		1	enabled
4	HMI		<b>half minute interrupt</b>
		0 <sup>[1]</sup>	disabled
		1	enabled
3	TF		<b>timer flag</b>
		0 <sup>[1]</sup>	no timer interrupt generated
		1	flag set when timer interrupt generated
2 to 0	COF[2:0]	see Table 11	<b>CLKOUT control</b>

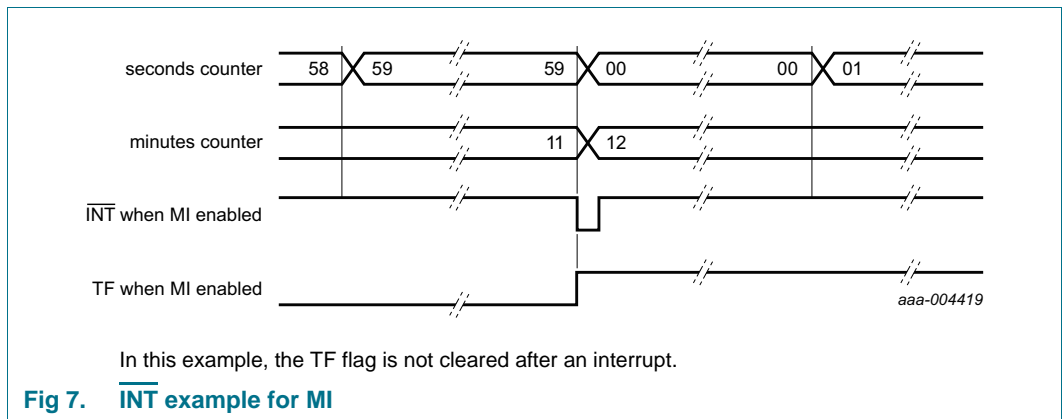
[1] Default value.

8.2.2.1 MI and HMI: minute and half minute interrupt

The minute interrupt (bit MI) and half minute interrupt (bit HMI) are pre-defined timers for generating interrupt pulses on pin  $\overline{\text{INT}}$ ; see Figure 7. The timers are running in sync with the seconds counter (see Table 19 on page 17).

The minute and half minute interrupts must only be used when the frequency offset is set to normal mode (MODE = 0), see Section 8.2.3. In normal mode, the interrupt pulses on pin  $\overline{\text{INT}}$  are  $\frac{1}{64}$  s wide.

When starting MI, the first interrupt will be generated after 1 second to 59 seconds. When starting HMI, the first interrupt will be generated after 1 second to 29 seconds. Subsequent periods do not have such a delay. The timers can be enabled independently from one another. However, a minute interrupt enabled on top of a half minute interrupt is not distinguishable.



**Table 10. Effect of bits MI and HMI on  $\overline{\text{INT}}$  generation**

Minute interrupt (bit MI)	Half minute interrupt (bit HMI)	Result
0	0	no interrupt generated
1	0	an interrupt every minute
0	1	an interrupt every 30 s
1	1	an interrupt every 30 s

The duration of the timer is affected by the register Offset (see [Section 8.2.3](#)). Only when OFFSET[6:0] has the value 00h the periods are consistent.

### 8.2.2.2 TF: timer flag

The timer flag (bit TF) is set logic 1 on the first trigger of MI or HMI and remains set until it is cleared by command.

### 8.2.2.3 COF[2:0]: Clock output frequency

A programmable square wave is available at pin CLKOUT. Operation is controlled by the COF[2:0] bits in the register Control\_2. Frequencies of 32.768 kHz (default) down to 1 Hz can be generated for use as a system clock, microcontroller clock, input to a charge pump, or for calibration of the oscillator.

Pin CLKOUT is a push-pull output and enabled at power-on. CLKOUT can be disabled by setting COF[2:0] to 111. When disabled, the CLKOUT is LOW.

The duty cycle of the selected clock is not controlled but due to the nature of the clock generation, all clock frequencies except 32.768 kHz have a duty cycle of 50 : 50.

The STOP bit function can also affect the CLKOUT signal, depending on the selected frequency. When the STOP bit is set logic 1, the CLKOUT pin generates a continuous LOW for those frequencies that can be stopped. For more details of the STOP bit function, see [Section 8.2.1.2](#).

**Table 11. CLKOUT frequency selection**

COF[2:0]	CLKOUT frequency (Hz)	Typical duty cycle <sup>[1]</sup>	Effect of STOP bit
000 <sup>[2]</sup>	32768	60 : 40 to 40 : 60	no effect
001	16384	50 : 50	no effect
010	8192	50 : 50	no effect
011	4096	50 : 50	CLKOUT = LOW
100	2048	50 : 50	CLKOUT = LOW
101	1024	50 : 50	CLKOUT = LOW
110	1 <sup>[3]</sup>	50 : 50	CLKOUT = LOW
111	CLKOUT = LOW	-	-

[1] Duty cycle definition: % HIGH-level time : % LOW-level time.

[2] Default value.

[3] 1 Hz clock pulses are affected by offset correction pulses.

### 8.2.3 Register Offset

The PCF85063TP incorporates an offset register (address 02h) which can be used to implement several functions, such as:

- Accuracy tuning
- Aging adjustment
- Temperature compensation

**Table 12. Offset - offset register (address 02h) bit description**

Bit	Symbol	Value	Description
7	MODE		<b>offset mode</b>
		0 <sup>[1]</sup>	normal mode: offset is made once every two hours
		1	course mode: offset is made every 4 minutes
6 to 0	OFFSET[6:0]	see <a href="#">Table 13</a>	<b>offset value</b>

[1] Default value.

For MODE = 0, each LSB introduces an offset of 4.34 ppm. For MODE = 1, each LSB introduces an offset of 4.069 ppm. The offset value is coded in two's complement giving a range of +63 LSB to -64 LSB.

**Table 13. Offset values**

OFFSET[6:0]	Offset value in decimal	Offset value in ppm	
		Normal mode MODE = 0	Fast mode MODE = 1
0111111	+63	+273.420	+256.347
0111110	+62	+269.080	+252.278
:	:	:	:
0000010	+2	+8.680	+8.138
0000001	+1	+4.340	+4.069
0000000 <sup>[1]</sup>	0	0 <sup>[1]</sup>	0 <sup>[1]</sup>
1111111	-1	-4.340	-4.069
1111110	-2	-8.680	-8.138
:	:	:	:
1000001	-63	-273.420	-256.347
1000000	-64	-277.760	-260.416

[1] Default value.

The correction is made by adding or subtracting clock correction pulses, thereby changing the period of a single second but not by changing the oscillator frequency.

It is possible to monitor when correction pulses are applied. To enable correction interrupt generation, bit CIE (register `Control_1`) has to be set logic 1. At every correction cycle a pulse is generated on pin INT. The pulse width depends on the correction mode. If multiple correction pulses are applied, an interrupt pulse is generated for each correction pulse applied.

8.2.3.1 Correction when MODE = 0

The correction is triggered once every two hours and then correction pulses are applied once per minute until the programmed correction values have been implemented.

Table 14. Correction pulses for MODE = 0

Correction value	Update every n <sup>th</sup> hour	Minute	Correction pulses on INT per minute <sup>[1]</sup>
+1 or -1	2	00	1
+2 or -2	2	00 and 01	1
+3 or -3	2	00, 01, and 02	1
:	:	:	:
+59 or -59	2	00 to 58	1
+60 or -60	2	00 to 59	1
+61 or -61	2	00 to 59	1
	2nd and next hour	00	1
+62 or -62	2	00 to 59	1
	2nd and next hour	00 and 01	1
+63 or -63	02	00 to 59	1
	2nd and next hour	00, 01, and 02	1
-64	02	00 to 59	1
	2nd and next hour	00, 01, 02, and 03	1

[1] The correction pulses on pin INT are 1/64 s wide.

In MODE = 0, any timer or clock output using a frequency below 64 Hz is affected by the clock correction (see Table 15).

Table 15. Effect of correction pulses on frequencies for MODE = 0

Frequency (Hz)	Effect of correction
<b>CLKOUT</b>	
32768	no effect
16384	no effect
8192	no effect
4096	no effect
2048	no effect
1024	no effect
1	affected
<b>Timer source clock</b>	
4096	no effect
64	no effect
1	affected
1/60	affected

8.2.3.2 Correction when MODE = 1

The correction is triggered once every four minutes and then correction pulses are applied once per second up to a maximum of 60 pulses. When correction values greater than 60 pulses are used, additional correction pulses are made in the 59<sup>th</sup> second.

Clock correction is made more frequently in MODE = 1; however, this can result in higher power consumption.

**Table 16. Correction pulses for MODE = 1**

Correction value	Update every n <sup>th</sup> minute	Second	Correction pulses on INT per second <sup>[1]</sup>
+1 or -1	2	00	1
+2 or -2	2	00 and 01	1
+3 or -3	2	00, 01, and 02	1
:	:	:	:
+59 or -59	2	00 to 58	1
+60 or -60	2	00 to 59	1
+61 or -61	2	00 to 58	1
	2	59	2
+62 or -62	2	00 to 58	1
	2	59	3
+63 or -63	2	00 to 58	1
	2	59	4
-64	2	00 to 58	1
	2	59	5

[1] The correction pulses on pin  $\overline{\text{INT}}$  are  $\frac{1}{1024}$  s wide. For multiple pulses, they are repeated at an interval of  $\frac{1}{512}$  s.

In MODE = 1, any timer source clock using a frequency below 1.024 kHz is also affected by the clock correction (see [Table 17](#)).

**Table 17. Effect of correction pulses on frequencies for MODE = 1**

Frequency (Hz)	Effect of correction
<b>CLKOUT</b>	
32768	no effect
16384	no effect
8192	no effect
4096	no effect
2048	no effect
1024	no effect
1	affected
<b>Timer source clock</b>	
4096	no effect
64	affected
1	affected
$\frac{1}{60}$	affected

8.2.3.3 Offset calibration workflow

The calibration offset has to be calculated based on the time. [Figure 8](#) shows the workflow how the offset register values can be calculated:

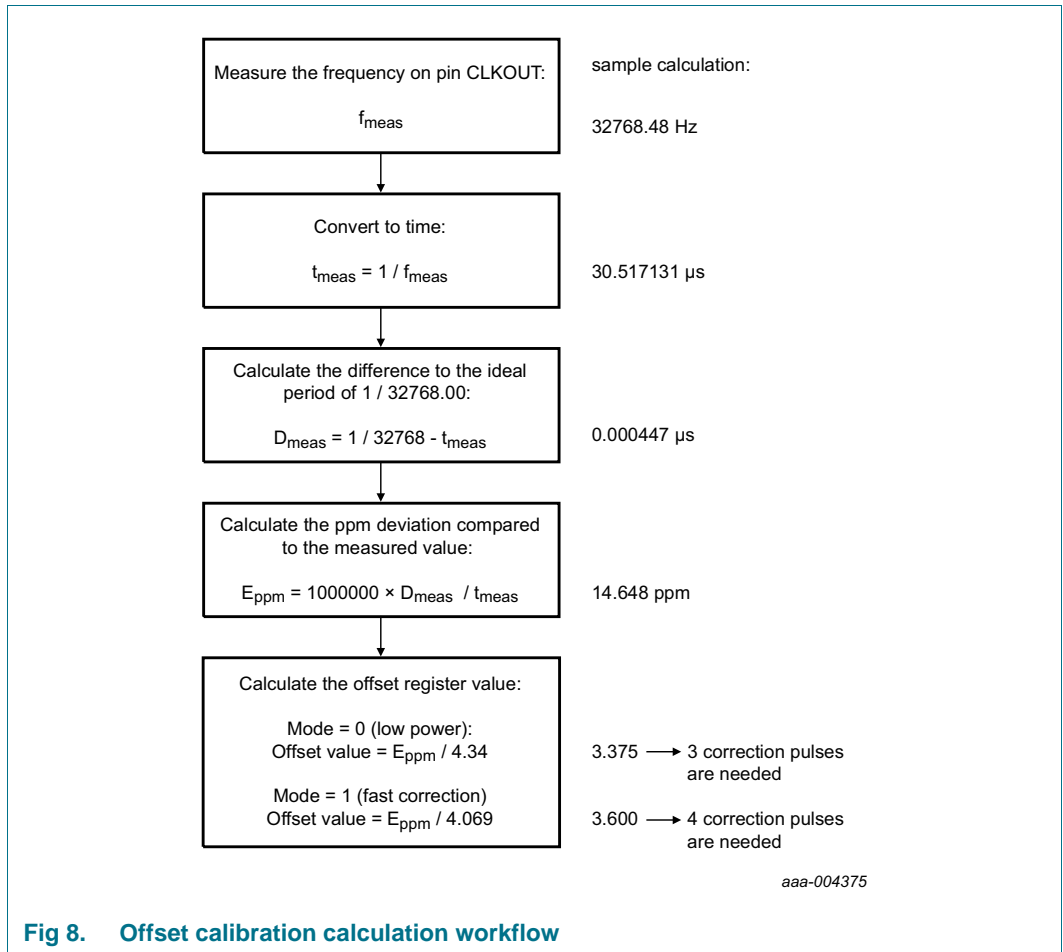
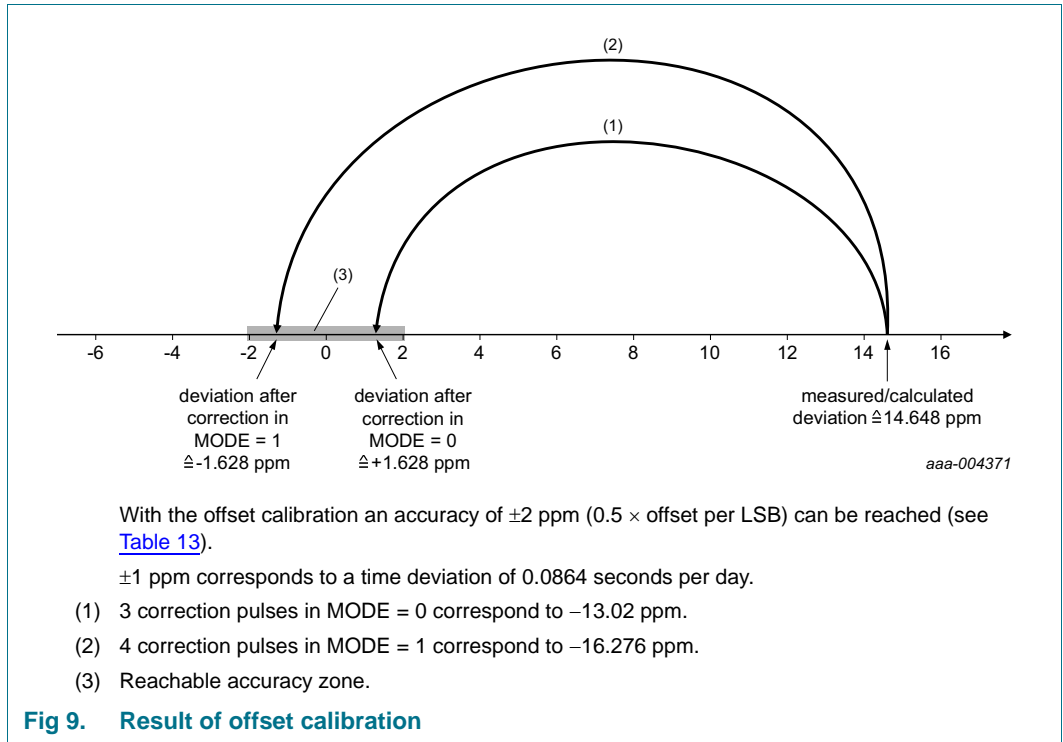


Fig 8. Offset calibration calculation workflow





**8.2.4 Register RAM\_byte**

The PCF85063TP provides a free RAM byte, which can be used for any purpose, for example, status byte of the system.

**Table 18. RAM\_byte - 8-bit RAM register (address 03h) bit description**

Bit	Symbol	Value	Description
7 to 0	B[7:0]	00000000 <sup>[1]</sup> to 11111111	RAM content

[1] Default value.

**8.3 Time and date registers**

Most of the registers are coded in the BCD format to simplify application use.

**8.3.1 Register Seconds**

**Table 19. Seconds - seconds register (address 04h) bit description**

Bit	Symbol	Value	Place value	Description
7	OS			<b>oscillator stop</b>
		0	-	clock integrity is guaranteed
		1 <sup>[1]</sup>	-	clock integrity is not guaranteed; oscillator has stopped or has been interrupted
6 to 4	SECONDS	0 <sup>[1]</sup> to 5	ten's place	<b>actual seconds</b> coded in BCD format, see <a href="#">Table 20</a>
3 to 0		0 <sup>[1]</sup> to 9	unit place	

[1] Default value.

Table 20. Seconds coded in BCD format

Seconds value in decimal	Upper-digit (ten's place)			Digit (unit place)			
	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
00 <sup>[1]</sup>	0	0	0	0	0	0	0
01	0	0	0	0	0	0	1
02	0	0	0	0	0	1	0
:	:	:	:	:	:	:	:
09	0	0	0	1	0	0	1
10	0	0	1	0	0	0	0
:	:	:	:	:	:	:	:
58	1	0	1	1	0	0	0
59	1	0	1	1	0	0	1

[1] Default value.

8.3.1.1 OS: Oscillator stop

When the oscillator of the PCF85063TP is stopped, the OS flag is set. The oscillator can be stopped, for example, by connecting one of the oscillator pins OSCI or OSCO to ground. The oscillator is considered to be stopped during the time between power-on and stable crystal resonance. This time can be in the range of 200 ms to 2 s depending on crystal type, temperature, and supply voltage.

The flag remains set until cleared by command (see Figure 10). If the flag cannot be cleared, then the oscillator is not running. This method can be used to monitor the oscillator and to determine if the supply voltage has reduced to the point where oscillation fails.

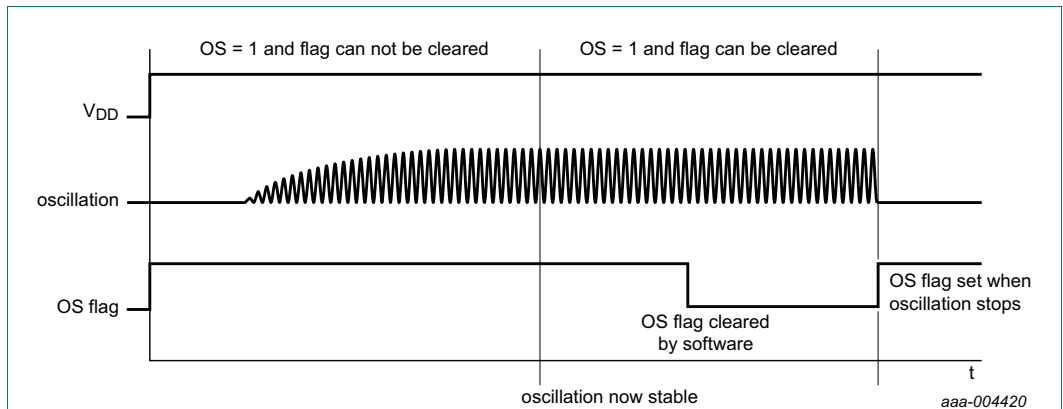


Fig 10. OS flag

### 8.3.2 Register Minutes

Table 21. Minutes - minutes register (address 05h) bit description

Bit	Symbol	Value	Place value	Description
7	-	0	-	unused
6 to 4	MINUTES	0 <sup>[1]</sup> to 5	ten's place	<b>actual minutes</b> coded in BCD format
3 to 0		0 <sup>[1]</sup> to 9	unit place	

[1] Default value.

### 8.3.3 Register Hours

Table 22. Hours - hours register (address 06h) bit description

Bit	Symbol	Value	Place value	Description
7 to 6	-	00	-	unused
<b>12 hour mode<sup>[1]</sup></b>				
5	AMPM			<b>AM/PM indicator</b>
		0 <sup>[2]</sup>	-	AM
		1	-	PM
4	HOURS	0 <sup>[2]</sup> to 1	ten's place	<b>actual hours in 12 hour mode</b> coded in BCD format
3 to 0		0 <sup>[2]</sup> to 9	unit place	
<b>24 hour mode<sup>[1]</sup></b>				
5 to 4	HOURS	0 <sup>[2]</sup> to 2	ten's place	<b>actual hours in 24 hour mode</b> coded in BCD format
3 to 0		0 <sup>[2]</sup> to 9	unit place	

[1] Hour mode is set by the 12\_24 bit in register Control\_1.

[2] Default value.

### 8.3.4 Register Days

Table 23. Days - days register (address 07h) bit description

Bit	Symbol	Value	Place value	Description
7 to 6	-	00	-	unused
5 to 4	DAYS <sup>[1]</sup>	0 <sup>[2]</sup> to 3	ten's place	<b>actual day</b> coded in BCD format
3 to 0		0 <sup>[3]</sup> to 9	unit place	

[1] If the year counter contains a value, which is exactly divisible by 4 (including the year 00), the PCF85063TP compensates for leap years by adding a 29th day to February.

[2] Default value.

[3] Default value is 1.

### 8.3.5 Register Weekdays

Table 24. Weekdays - weekdays register (address 08h) bit description

Bit	Symbol	Value	Description
7 to 3	-	00000	unused
2 to 0	WEEKDAYS	0 to 6	<b>actual weekday</b> values, see <a href="#">Table 25</a>

Table 25. Weekday assignments

Day <sup>[1]</sup>	Bit		
	2	1	0
Sunday	0	0	0
Monday	0	0	1
Tuesday	0	1	0
Wednesday	0	1	1
Thursday	1	0	0
Friday	1	0	1
Saturday <sup>[2]</sup>	1	1	0

[1] Definition may be reassigned by the user.

[2] Default value.

### 8.3.6 Register Months

Table 26. Months - months register (address 09h) bit description

Bit	Symbol	Value	Place value	Description
7 to 5	-	000	-	unused
4	MONTHS	0 to 1	ten's place	<b>actual month</b> coded in BCD format, see <a href="#">Table 27</a>
3 to 0		0 to 9	unit place	

Table 27. Month assignments in BCD format

Month	Upper-digit (ten's place)	Digit (unit place)			
	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
January <sup>[1]</sup>	0	0	0	0	1
February	0	0	0	1	0
March	0	0	0	1	1
April	0	0	1	0	0
May	0	0	1	0	1
June	0	0	1	1	0
July	0	0	1	1	1
August	0	1	0	0	0
September	0	1	0	0	1
October	1	0	0	0	0
November	1	0	0	0	1
December	1	0	0	1	0

[1] Default value.

### 8.3.7 Register Years

Table 28. Years - years register (0Ah) bit description

Bit	Symbol	Value	Place value	Description
7 to 4	YEARS	0 <sup>[1]</sup> to 9	ten's place	<b>actual year</b> coded in BCD format
3 to 0		0 <sup>[1]</sup> to 9	unit place	

[1] Default value.

### 8.4 Setting and reading the time

Figure 11 shows the data flow and data dependencies starting from the 1 Hz clock tick.

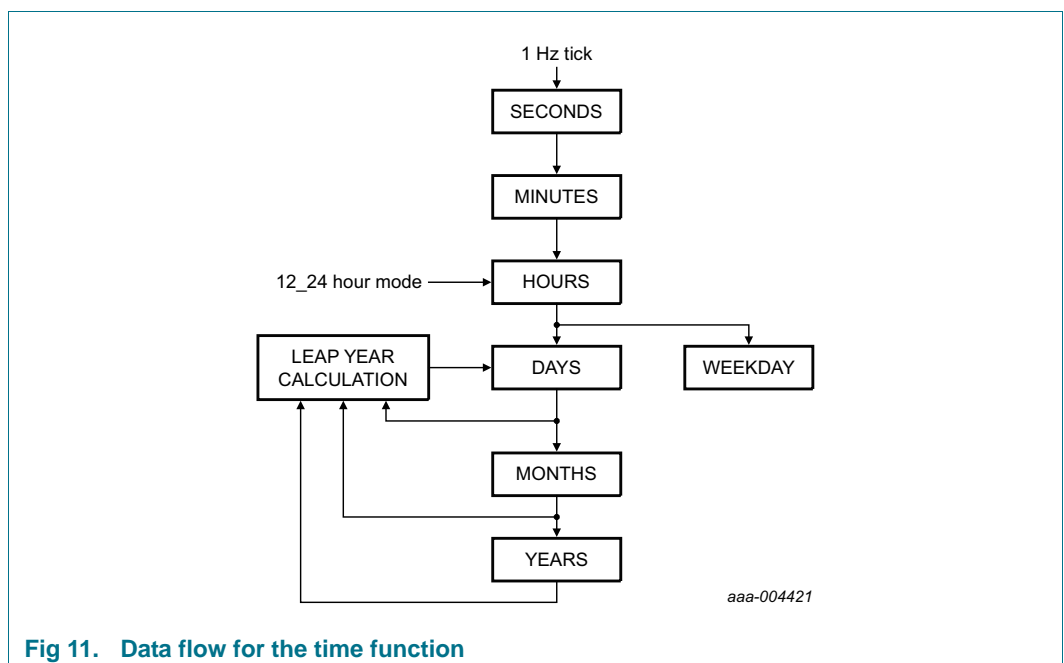


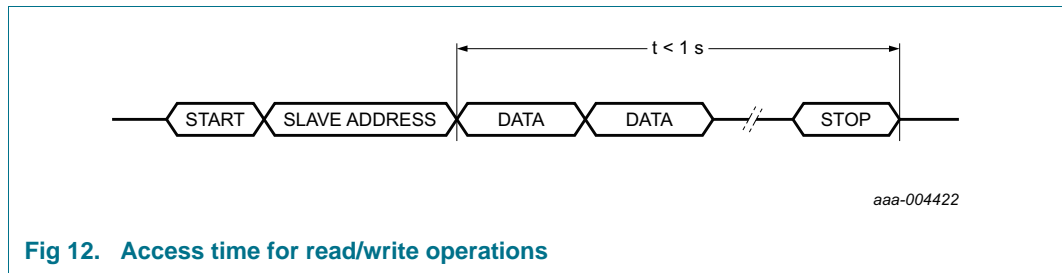
Fig 11. Data flow for the time function

During read/write operations, the time counting circuits (memory locations 04h through 0Ah) are blocked.

The blocking prevents

- Faulty reading of the clock and calendar during a carry condition
- Incrementing the time registers during the read cycle

After this read/write access is completed, the time circuit is released again and any pending request to increment the time counters that occurred during the read/write access is serviced. A maximum of 1 request can be stored; therefore, all accesses must be completed within 1 second (see Figure 12).



**Fig 12. Access time for read/write operations**

Because of this method, it is very important to make a read or write access in one go, that is, setting or reading seconds through to years should be made in one single access. Failing to comply with this method could result in the time becoming corrupted.

As an example, if the time (seconds through to hours) is set in one access and then in a second access the date is set, it is possible that the time will increment between the two accesses. A similar problem exists when reading. A roll-over may occur between reads thus giving the minutes from one moment and the hours from the next.

Recommended method for reading the time:

1. Send a START condition and the slave address (see [Table 29 on page 25](#)) for write (A2h)
2. Set the address pointer to 4 (Seconds) by sending 04h
3. Send a RESTART condition or STOP followed by START
4. Send the slave address for read (A3h)
5. Read Seconds
6. Read Minutes
7. Read Hours
8. Read Days
9. Read Weekdays
10. Read Months
11. Read Years
12. Send a STOP condition

## 9. Characteristics of the I<sup>2</sup>C-bus interface

The I<sup>2</sup>C-bus is for bidirectional, two-line communication between different ICs or modules. The two lines are a Serial DAta line (SDA) and a Serial CLock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor. Data transfer may be initiated only when the bus is not busy.

### 9.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse, as changes in the data line at this time are interpreted as a control signal (see [Figure 13](#)).

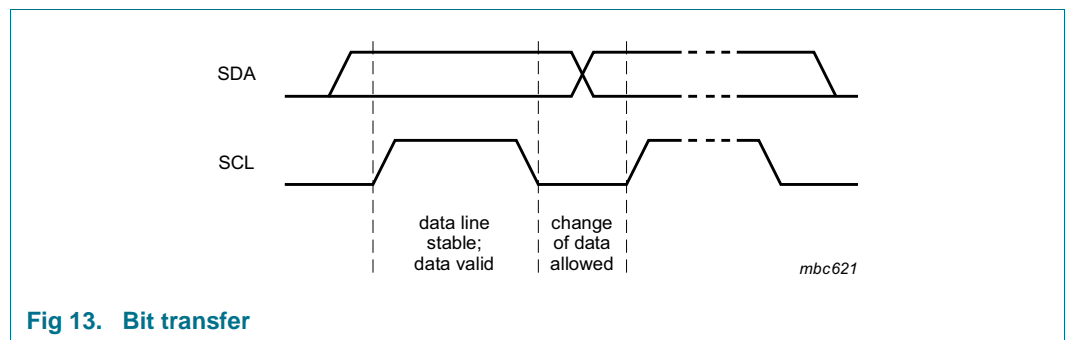


Fig 13. Bit transfer

### 9.2 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy.

A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as the START condition - S.

A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition - P (see [Figure 14](#)).

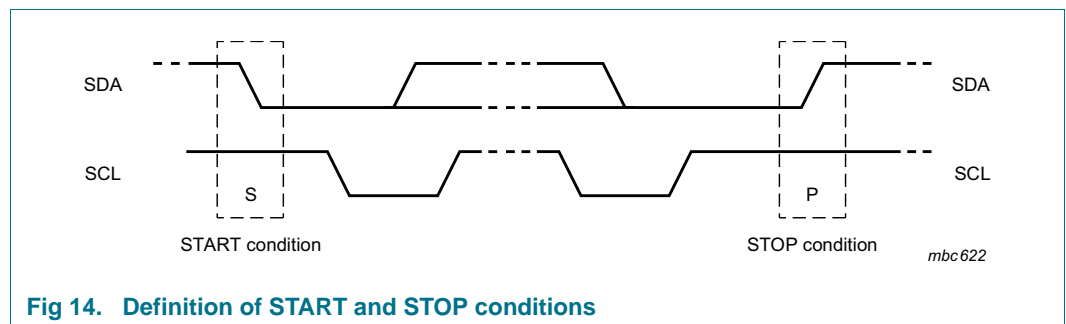


Fig 14. Definition of START and STOP conditions

### 9.3 System configuration

A device generating a message is a transmitter; a device receiving a message is a receiver. The device that controls the message is the master; and the devices which are controlled by the master are the slaves (see [Figure 15](#)).

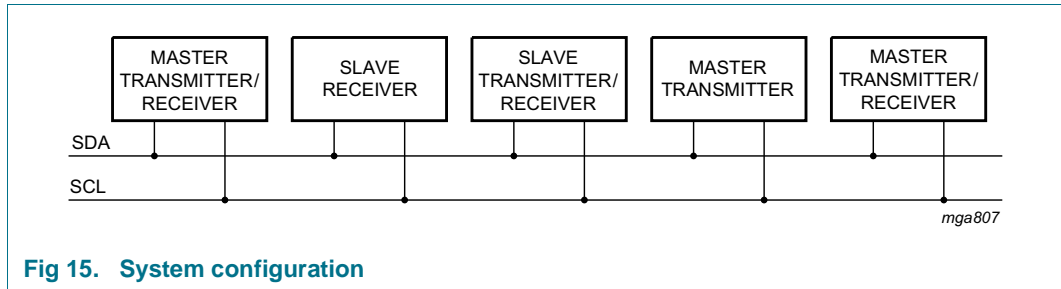


Fig 15. System configuration

### 9.4 Acknowledge

The number of data bytes transferred between the START and STOP conditions from transmitter to receiver is unlimited. Each byte of 8 bits is followed by an acknowledge cycle.

- A slave receiver, which is addressed, must generate an acknowledge after the reception of each byte
- Also a master receiver must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter
- The device that acknowledges must pull-down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse (set-up and hold times must be considered)
- A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition

Acknowledgement on the I<sup>2</sup>C-bus is shown in [Figure 16](#).

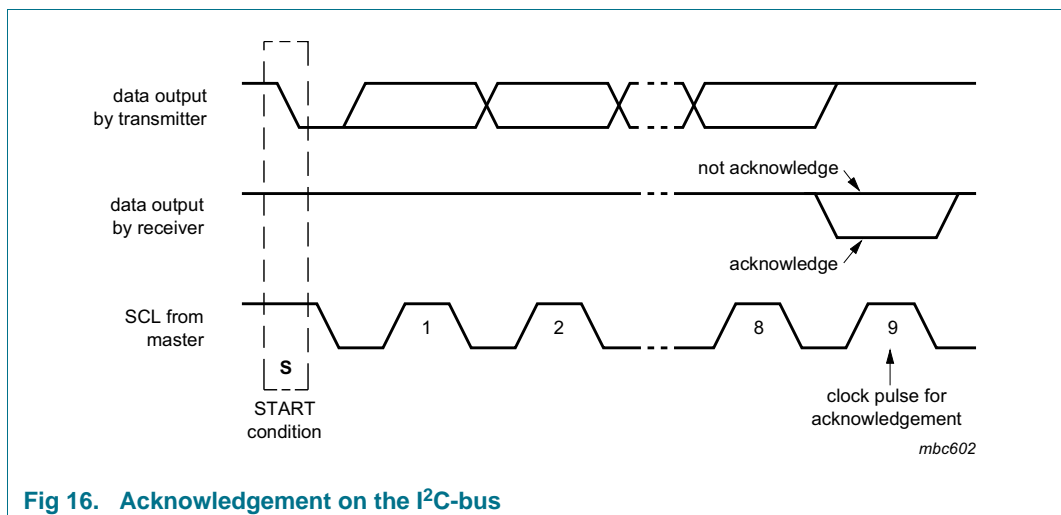


Fig 16. Acknowledgement on the I<sup>2</sup>C-bus



## 9.5 I<sup>2</sup>C-bus protocol

### 9.5.1 Addressing

One I<sup>2</sup>C-bus slave address (1010001) is reserved for the PCF85063TP. The entire I<sup>2</sup>C-bus slave address byte is shown in [Table 29](#).

**Table 29. I<sup>2</sup>C slave address byte**

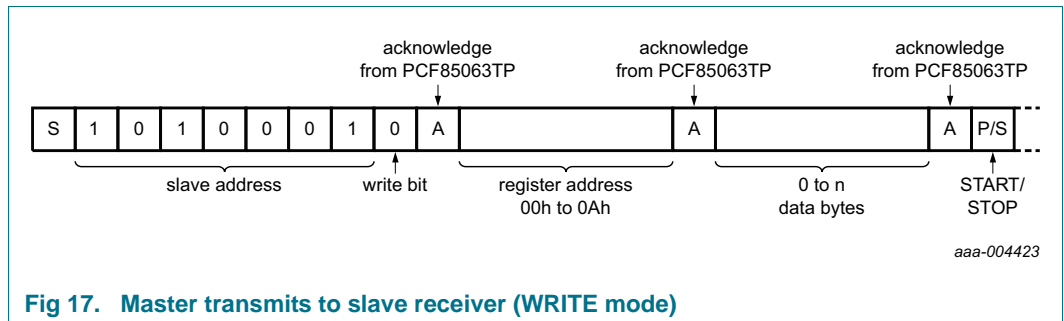
		Slave address							
Bit	7	6	5	4	3	2	1	0	
	MSB							LSB	
	1	0	1	0	0	0	1	R/W	

After a START condition, the I<sup>2</sup>C slave address has to be sent to the PCF85063TP device.

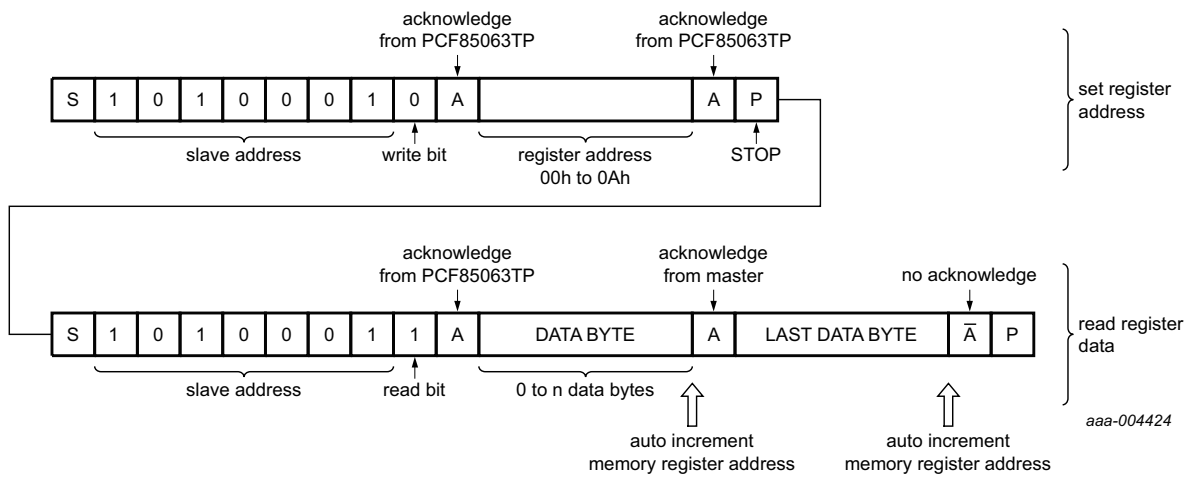
The R/W bit defines the direction of the following single or multiple byte data transfer (R/W = 0 for writing, R/W = 1 for reading). For the format and the timing of the START condition (S), the STOP condition (P) and the acknowledge bit (A) refer to the I<sup>2</sup>C-bus characteristics (see [Ref. 12 "UM10204"](#)). In the write mode, a data transfer is terminated by sending either the STOP condition or the START condition of the next data transfer.

### 9.5.2 Clock and calendar READ or WRITE cycles

The I<sup>2</sup>C-bus configuration for the different PCF85063TP READ and WRITE cycles is shown in [Figure 17](#) and [Figure 18](#). The register address is a 4-bit value that defines which register will be accessed next. The upper 4 bits of the register address are not used.



**Fig 17. Master transmits to slave receiver (WRITE mode)**



For multimaster configurations and to fasten the communication, the STOP-START sequence can be replaced by a repeated START (Sr).

**Fig 18. Master reads after setting register address (WRITE register address; READ data)**

## 10. Internal circuitry

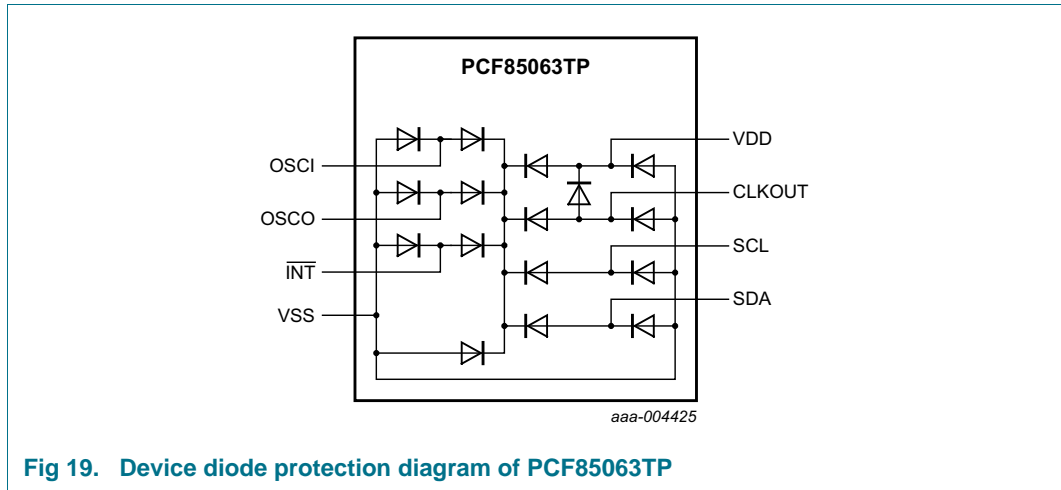


Fig 19. Device diode protection diagram of PCF85063TP

## 11. Safety notes

### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

## 12. Limiting values

**Table 30. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit	
V <sub>DD</sub>	supply voltage		-0.5	+6.5	V	
I <sub>DD</sub>	supply current		-50	+50	mA	
V <sub>I</sub>	input voltage	on pins SCL, SDA, OSCI	-0.5	+6.5	V	
V <sub>O</sub>	output voltage		-0.5	+6.5	V	
I <sub>I</sub>	input current	at any input	-10	+10	mA	
I <sub>O</sub>	output current	at any output	-10	+10	mA	
P <sub>tot</sub>	total power dissipation		-	300	mW	
V <sub>ESD</sub>	electrostatic discharge voltage	HBM	[1]	-	±5000	V
		CDM	[2]	-	±1500	V
I <sub>lu</sub>	latch-up current		[3]	-	200	mA
T <sub>stg</sub>	storage temperature		[4]	-65	+150	°C
T <sub>amb</sub>	ambient temperature	operating device	-40	+85	°C	

[1] Pass level; Human Body Model (HBM) according to [Ref. 7 "JESD22-A114"](#).

[2] Pass level; Charged-Device Model (CDM), according to [Ref. 8 "JESD22-C101"](#).

[3] Pass level; latch-up testing, according to [Ref. 9 "JESD78"](#) at maximum ambient temperature (T<sub>amb(max)</sub>).

[4] According to the store and transport requirements (see [Ref. 14 "UM10569"](#)) the devices have to be stored at a temperature of +8 °C to +45 °C and a humidity of 25 % to 75 %.

### 13. Characteristics

**Table 31. Static characteristics**

$V_{DD} = 0.9\text{ V to }5.5\text{ V}$ ;  $V_{SS} = 0\text{ V}$ ;  $T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ ;  $f_{osc} = 32.768\text{ kHz}$ ; quartz  $R_s = 60\text{ k}\Omega$ ;  $C_L = 7\text{ pF}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Supplies</b>							
V <sub>DD</sub>	supply voltage	interface inactive; f <sub>SCL</sub> = 0 Hz	[1] 0.9	-	5.5	V	
		interface active; f <sub>SCL</sub> = 400 kHz	[1] 1.8	-	5.5	V	
I <sub>DD</sub>	supply current	V <sub>DD</sub> = 3.3 V	[2]				
		interface inactive; f <sub>SCL</sub> = 0 Hz					
		T <sub>amb</sub> = 25 °C	-	220	450	nA	
		T <sub>amb</sub> = 50 °C	[3]	-	250	500	nA
		T <sub>amb</sub> = 85 °C	-	-	470	600	nA
		interface active; f <sub>SCL</sub> = 400 kHz	-	18	50	μA	
<b>Inputs</b> [4]							
V <sub>I</sub>	input voltage		V <sub>SS</sub>	-	5.5	V	
V <sub>IL</sub>	LOW-level input voltage		V <sub>SS</sub>	-	0.3V <sub>DD</sub>	V	
V <sub>IH</sub>	HIGH-level input voltage		0.7V <sub>DD</sub>	-	V <sub>DD</sub>	V	
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>SS</sub> or V <sub>DD</sub>	-	0	-	μA	
		post ESD event	-0.15	-	+0.15	μA	
C <sub>i</sub>	input capacitance		[5]	-	7	pF	
<b>Outputs</b>							
V <sub>OH</sub>	HIGH-level output voltage	on pin CLKOUT	0.8V <sub>DD</sub>	-	V <sub>DD</sub>	V	
V <sub>OL</sub>	LOW-level output voltage	on pins SDA, INT, CLKOUT	V <sub>SS</sub>	-	0.2V <sub>DD</sub>	V	
I <sub>OH</sub>	HIGH-level output current	output source current; V <sub>OH</sub> = 2.9 V; V <sub>DD</sub> = 3.3 V; on pin CLKOUT	1	3	-	mA	
I <sub>OL</sub>	LOW-level output current	output sink current; V <sub>OL</sub> = 0.4 V; V <sub>DD</sub> = 3.3 V					
		on pin SDA	3	8.5	-	mA	
		on pin INT	2	6	-	mA	
		on pin CLKOUT	1	3	-	mA	

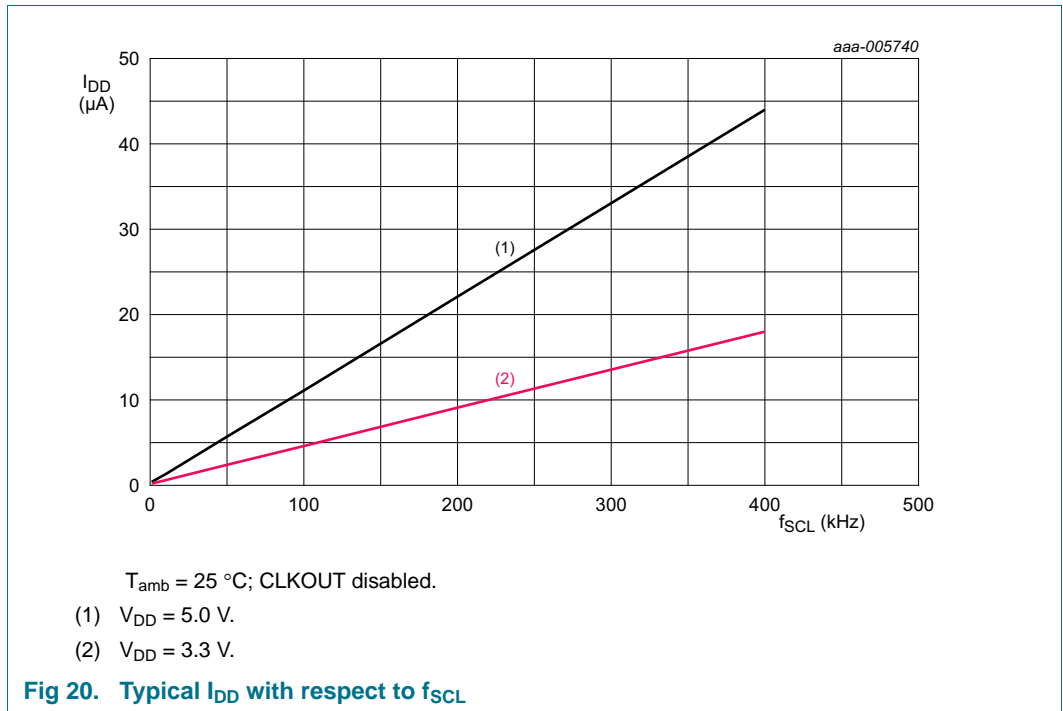
**Table 31. Static characteristics ...continued**

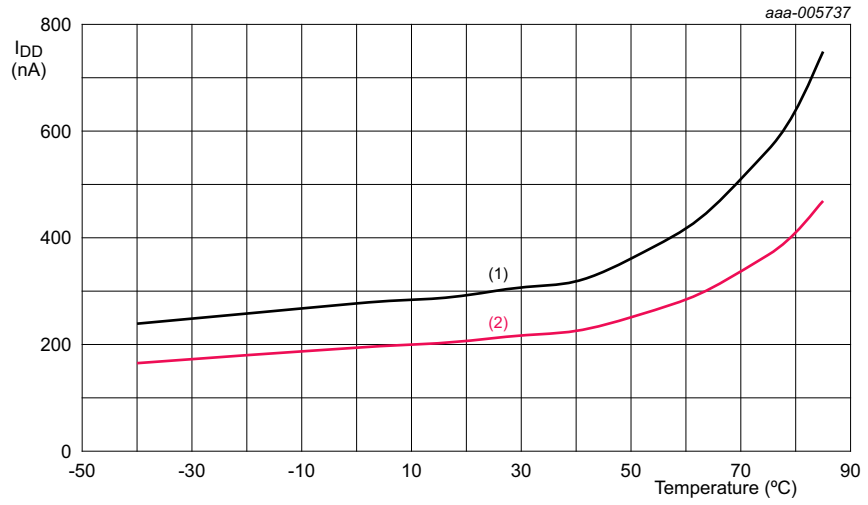
$V_{DD} = 0.9\text{ V to }5.5\text{ V}$ ;  $V_{SS} = 0\text{ V}$ ;  $T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ ;  $f_{osc} = 32.768\text{ kHz}$ ; quartz  $R_s = 60\text{ k}\Omega$ ;  $C_L = 7\text{ pF}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Oscillator</b>						
$\Delta f_{osc}/f_{osc}$	relative oscillator frequency variation	$\Delta V_{DD} = 200\text{ mV}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	0.075	-	ppm
$C_{L(itg)}$	integrated load capacitance	on pins OSCO, OSC1 [6]				
		$C_L = 7\text{ pF}$	4.2	7	9.8	pF
		$C_L = 12.5\text{ pF}$	7.5	12.5	17.5	pF
$R_s$	series resistance		-	-	100	k $\Omega$

- [1] For reliable oscillator start-up at power-on:  $V_{DD(po)min} = V_{DD(min)} + 0.3\text{ V}$ .
- [2] Timer source clock =  $1/60\text{ Hz}$ , level of pins SCL and SDA is  $V_{DD}$  or  $V_{SS}$ .
- [3] Tested on sample basis.
- [4] The I<sup>2</sup>C-bus interface of PCF85063TP is 5 V tolerant.
- [5] Implicit by design.

[6] Integrated load capacitance,  $C_{L(itg)}$ , is a calculation of  $C_{OSCI}$  and  $C_{OSCO}$  in series: 
$$C_{L(itg)} = \frac{(C_{OSCI} \cdot C_{OSCO})}{(C_{OSCI} + C_{OSCO})}$$

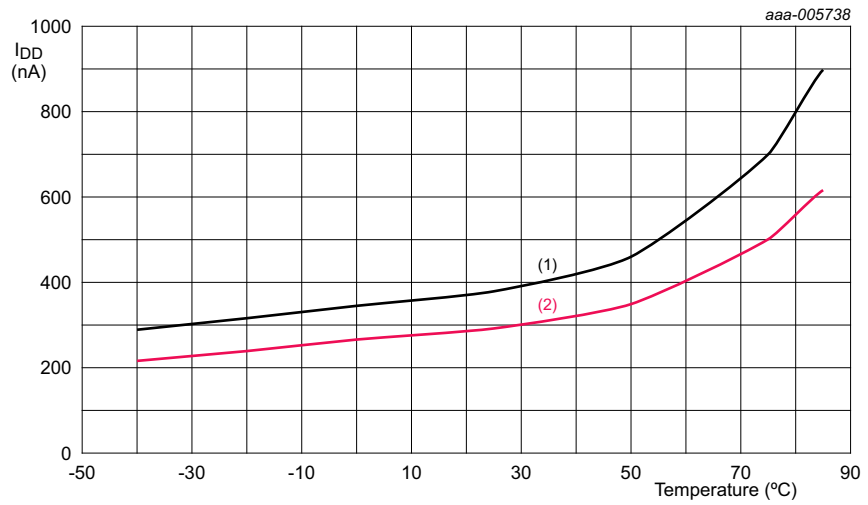




$C_{L(itg)} = 7 \text{ pF}$ ; CLKOUT disabled.

(1)  $V_{DD} = 5.5 \text{ V}$ .

(2)  $V_{DD} = 3.3 \text{ V}$ .

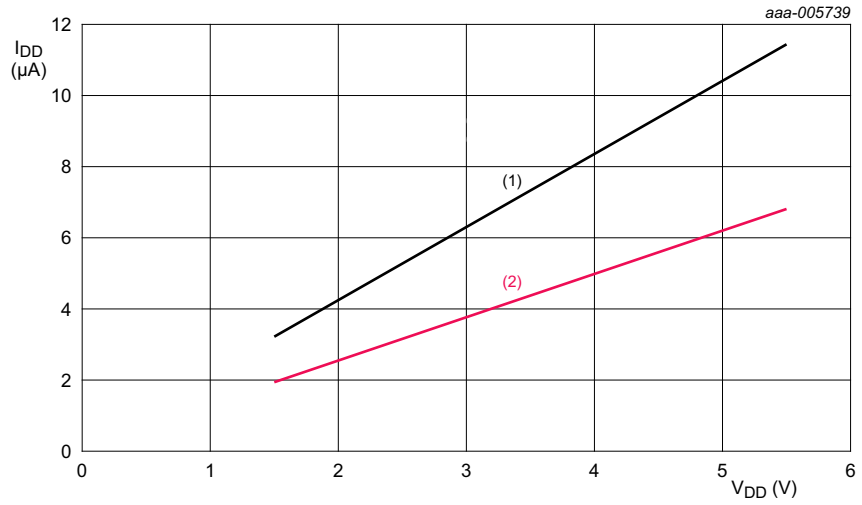


$C_{L(itg)} = 12.5 \text{ pF}$ ; CLKOUT disabled.

(1)  $V_{DD} = 5.5 \text{ V}$ .

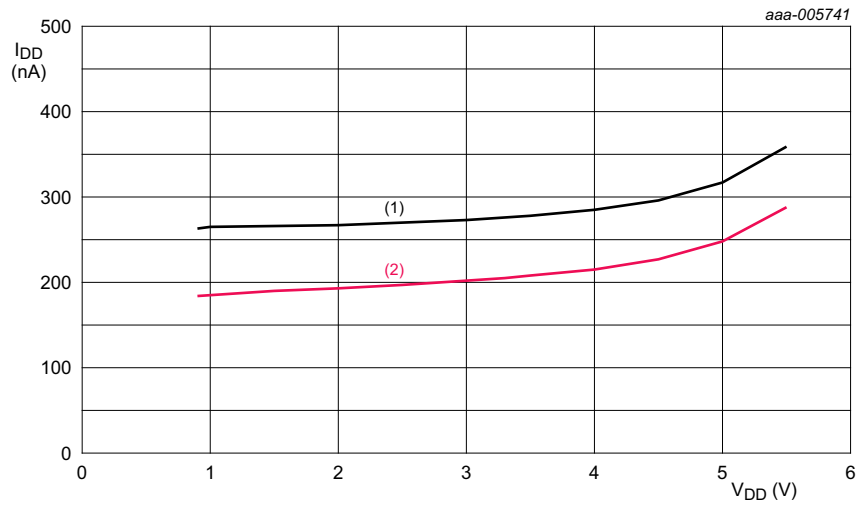
(2)  $V_{DD} = 3.3 \text{ V}$ .

**Fig 21. Typical I<sub>DD</sub> as a function of temperature**



T<sub>amb</sub> = 25 °C; f<sub>CLKOUT</sub> = 32768 Hz.

- (1) 47 pF CLKOUT load.
- (2) 22 pF CLKOUT load.

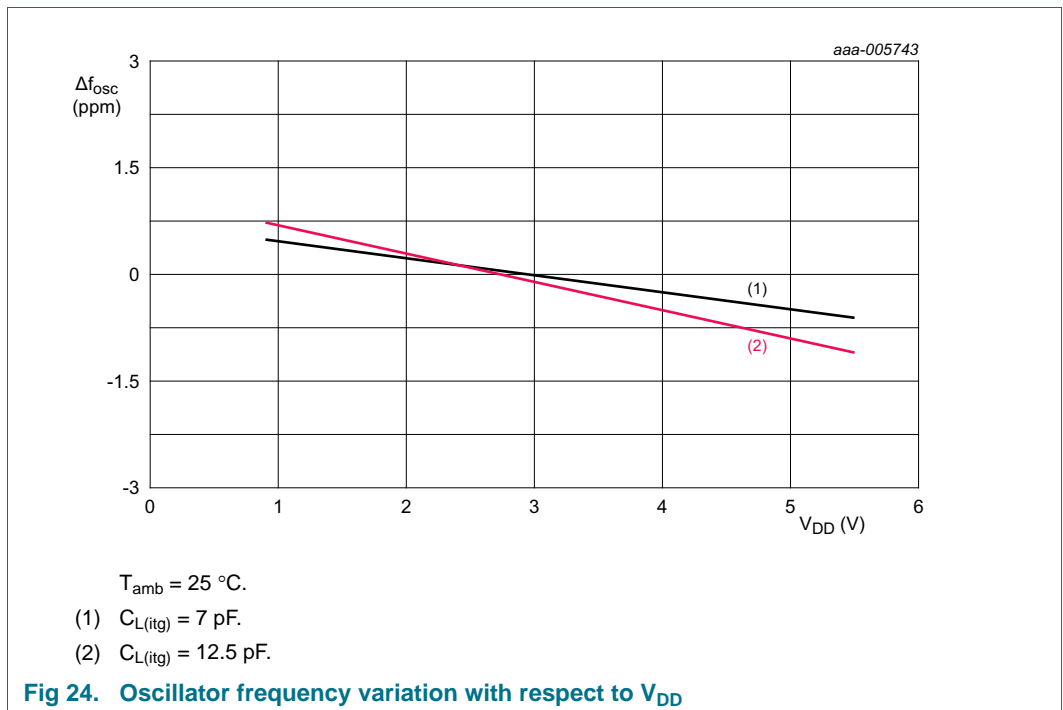
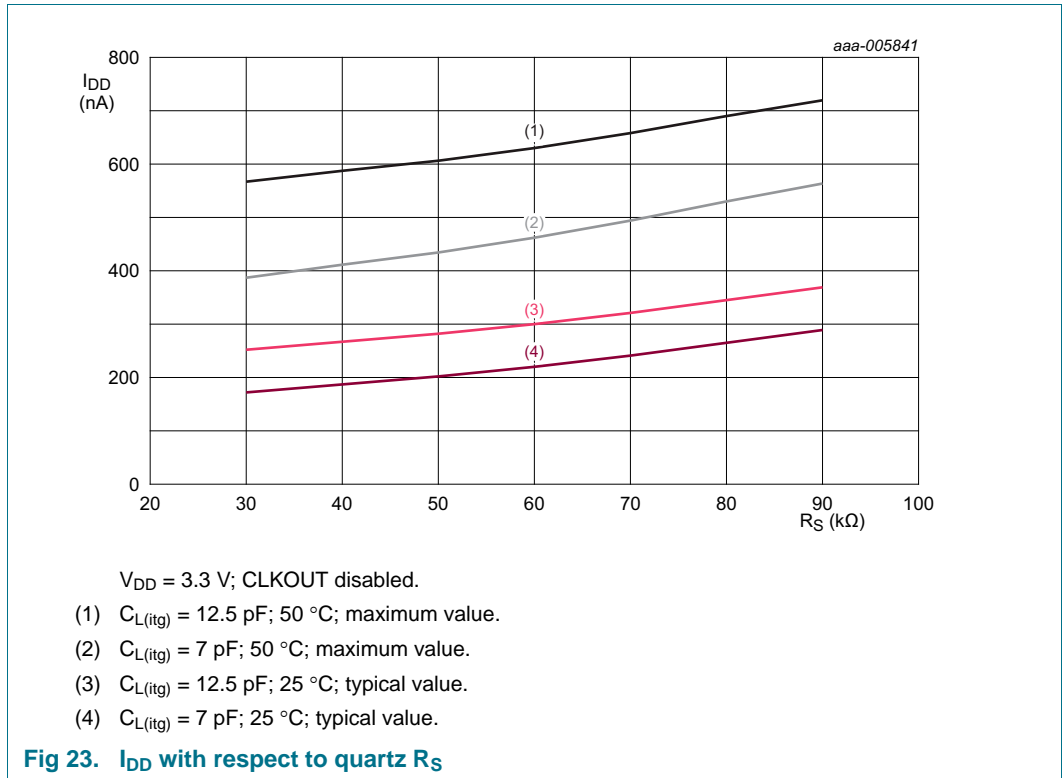


T<sub>amb</sub> = 25 °C; CLKOUT disabled.

- (1) C<sub>L(itg)</sub> = 12.5 pF.
- (2) C<sub>L(itg)</sub> = 7 pF.

**Fig 22. Typical I<sub>DD</sub> with respect to V<sub>DD</sub>**





**Table 32. I<sup>2</sup>C-bus characteristics**

$V_{DD} = 1.8\text{ V to }5.5\text{ V}$ ;  $V_{SS} = 0\text{ V}$ ;  $T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ ;  $f_{osc} = 32.768\text{ kHz}$ ; quartz  $R_s = 60\text{ k}\Omega$ ;  $C_L = 7\text{ pF}$ ; unless otherwise specified. All timing values are valid within the operating supply voltage and temperature range and referenced to  $V_{IL}$  and  $V_{IH}$  with an input voltage swing of  $V_{SS}$  to  $V_{DD}$ [1].

Symbol	Parameter	Conditions	Min	Max	Unit
$C_b$	capacitive load for each bus line		-	400	pF
$f_{SCL}$	SCL clock frequency	[2]	0	400	kHz
$t_{HD;STA}$	hold time (repeated) START condition		0.6	-	$\mu\text{s}$
$t_{SU;STA}$	set-up time for a repeated START condition		0.6	-	$\mu\text{s}$
$t_{LOW}$	LOW period of the SCL clock		1.3	-	$\mu\text{s}$
$t_{HIGH}$	HIGH period of the SCL clock		0.6	-	$\mu\text{s}$
$t_r$	rise time of both SDA and SCL signals		20	300	ns
$t_f$	fall time of both SDA and SCL signals	[3][4]	$20 \times (V_{DD} / 5.5\text{ V})$	300	ns
$t_{BUF}$	bus free time between a STOP and START condition		1.3	-	$\mu\text{s}$
$t_{SU;DAT}$	data set-up time		100	-	ns
$t_{HD;DAT}$	data hold time		0	-	ns
$t_{SU;STO}$	set-up time for STOP condition		0.6	-	$\mu\text{s}$
$t_{VD;DAT}$	data valid time		0	0.9	$\mu\text{s}$
$t_{VD;ACK}$	data valid acknowledge time		0	0.9	$\mu\text{s}$
$t_{SP}$	pulse width of spikes that must be suppressed by the input filter		0	50	ns

[1] A detailed description of the I<sup>2</sup>C-bus specification is given in [Ref. 12 "UM10204"](#).

[2] I<sup>2</sup>C-bus access time between two STARTs or between a START and a STOP condition to this device must be less than one second.

[3] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the  $V_{IH(\min)}$  of the SCL signal) to bridge the undefined region of the falling edge of SCL.

[4] The maximum  $t_f$  for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage  $t_f$  is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified  $t_f$ .

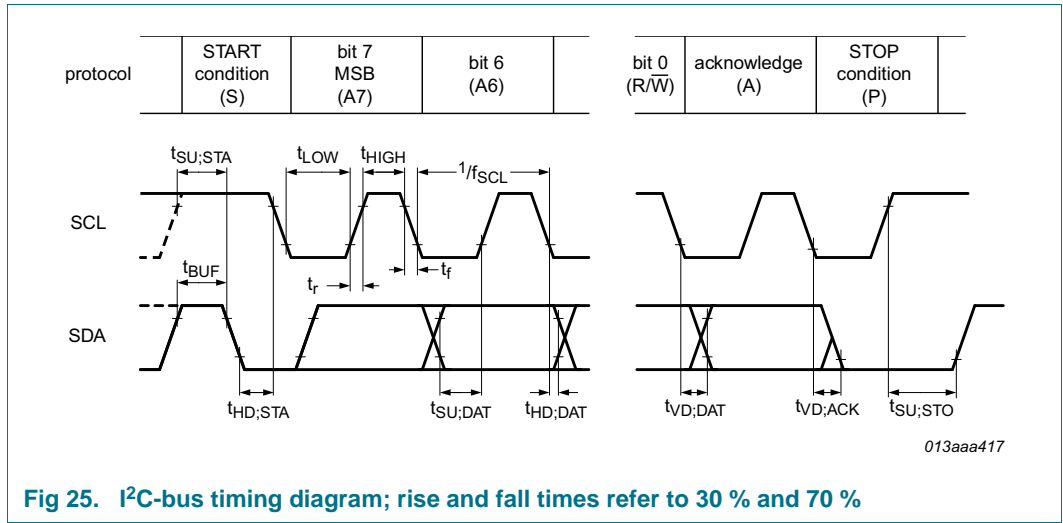
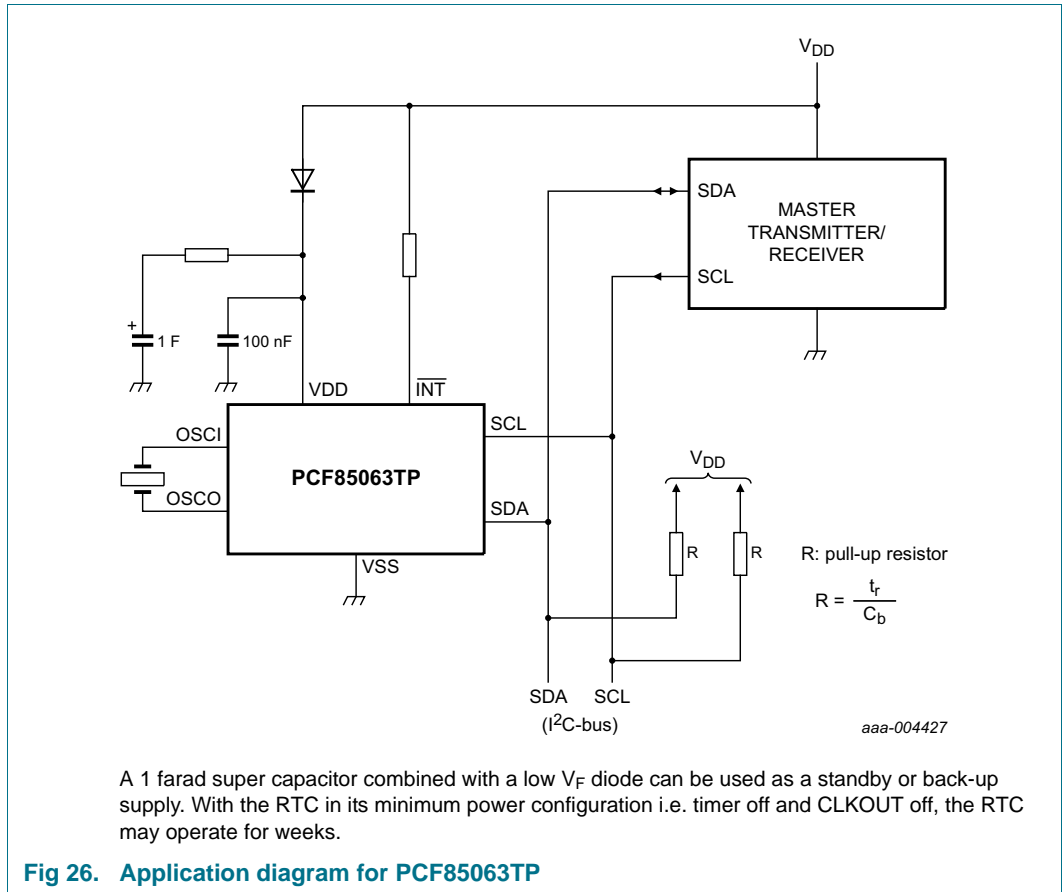


Fig 25. I<sup>2</sup>C-bus timing diagram; rise and fall times refer to 30 % and 70 %

14. Application information



15. Package outline

HWSON8: plastic thermal enhanced very very thin small outline package; no leads; 8 terminals; body 2 x 3 x 0.75 mm

SOT1069-2

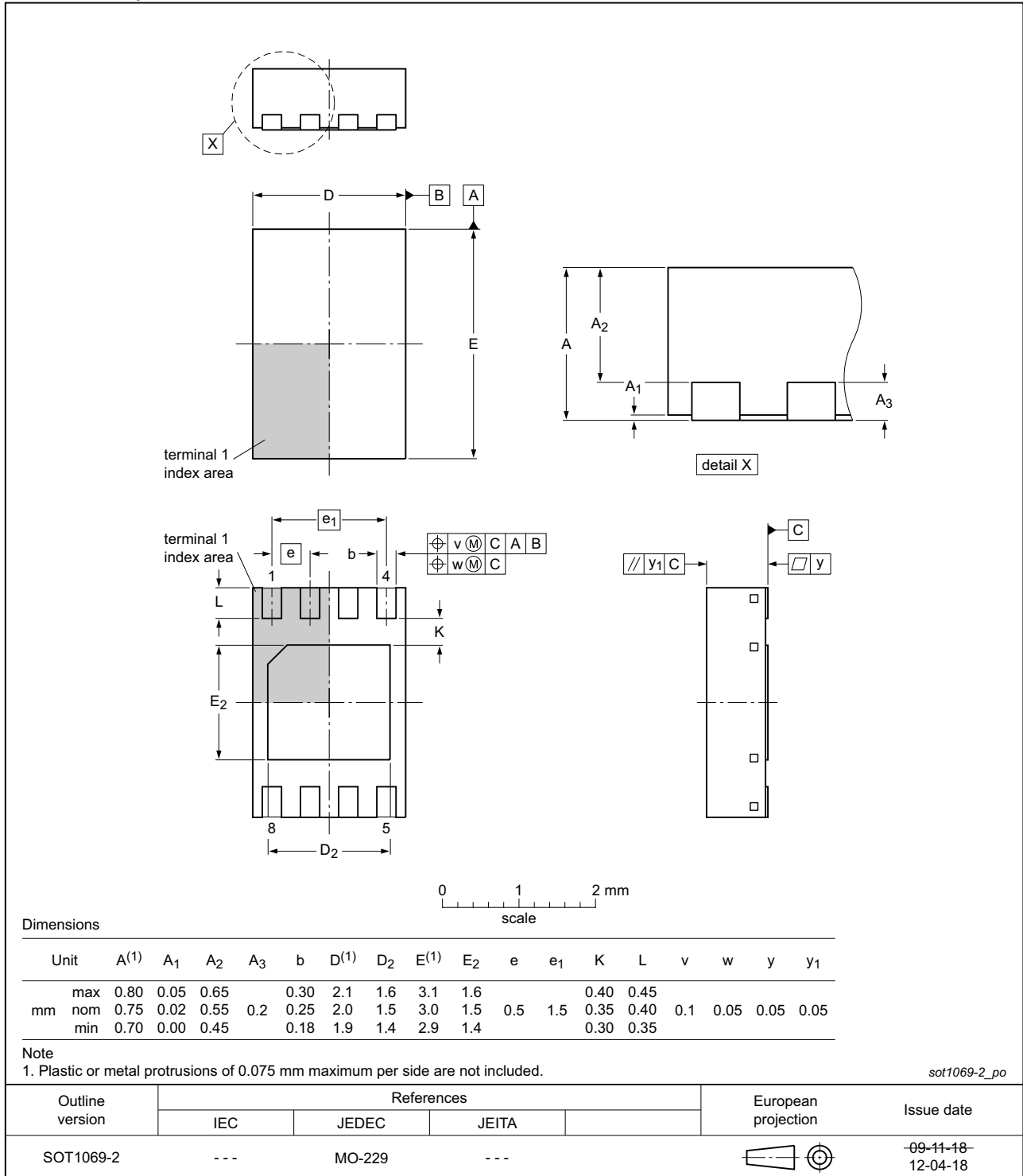


Fig 27. Package outline SOT1069-2 (HWSON8) of PCF85063TP

## 16. Handling information

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All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling Metal-Oxide Semiconductor (MOS) devices ensure that all normal precautions are taken as described in *JESD625-A*, *IEC 61340-5* or equivalent standards.

## 17. Packing information

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### 17.1 Tape and reel information

For tape and reel packing information, see [Ref. 11 "SOT1069-2\\_147"](#).

## 18. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

### 18.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

### 18.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

### 18.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

### 18.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 28](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 33](#) and [34](#)

**Table 33. SnPb eutectic process (from J-STD-020D)**

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm <sup>3</sup> )	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

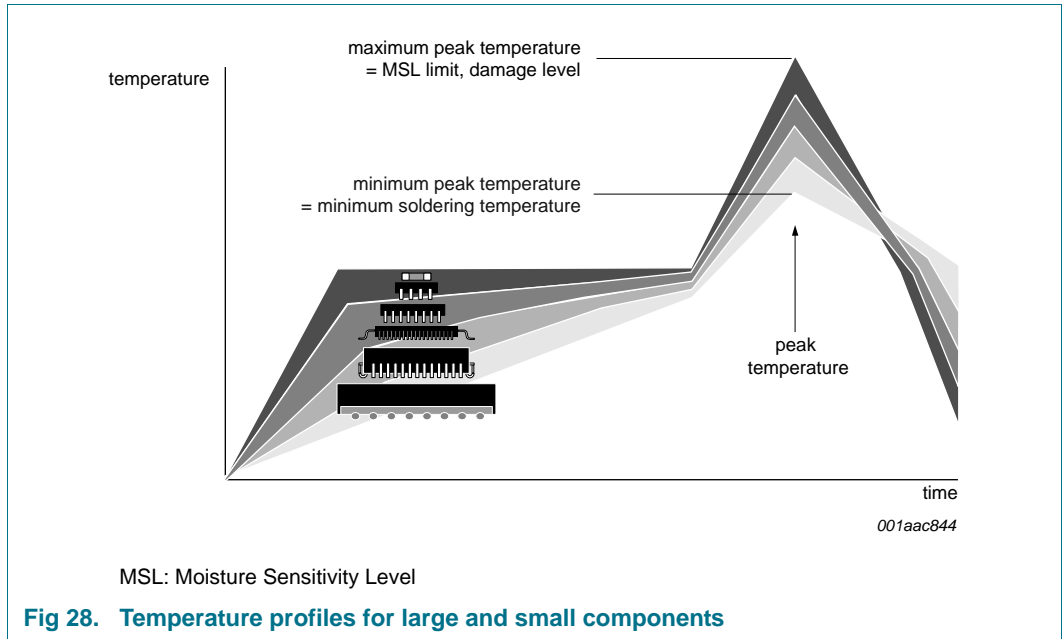
**Table 34. Lead-free process (from J-STD-020D)**

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm <sup>3</sup> )		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 28](#).



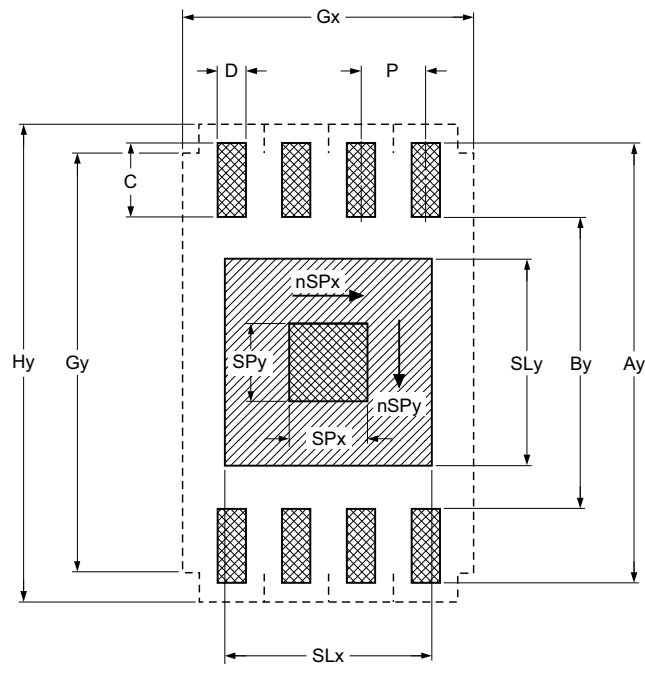





For further information on temperature profiles, refer to Application Note AN10365 “Surface mount reflow soldering description”.

## 19. Footprint information

Footprint information for reflow soldering of HWSON8 package

SOT1069-2



-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

DIMENSIONS in mm

P	Ay	By	C	D	SLx	SLy	SPx	SPy	Gx	GY	Hy
0.5	3.45	2.2	0.625	0.25	1.6	1.6	0.6	0.6	2.25	3.25	3.7

nSPx	nSPy
1	1

Issue date 12-02-09  
12-02-22

sot1069-2\_fr

Fig 29. Footprint information for reflow soldering of SOT1069-2 (HWSON8) of PCF85063TP

## 20. Appendix

### 20.1 Real-Time Clock selection

Table 35. Selection of Real-Time Clocks

Type name	Alarm, Timer, Watchdog	Interrupt output	Interface	I <sub>DD</sub> , typical (nA)	Battery backup	Timestamp, tamper input	AEC-Q100 compliant	Special features	Packages
PCF85063TP	-	1	I <sup>2</sup> C	220	-	-	-	basic functions only, no alarm	HXSON8
PCF85063A	X	1	I <sup>2</sup> C	220	-	-	-	tiny package	SO8, DFN2626-10, TSSOP8
PCF85063B	X	1	SPI	220	-	-	-	tiny package	DFN2626-10
PCF85263A	X	2	I <sup>2</sup> C	230	X	X	-	time stamp, battery backup, stopwatch 1/100 s	SO8, TSSOP10, TSSOP8, DFN2626-10
PCF85263B	X	2	SPI	230	X	X	-	time stamp, battery backup, stopwatch 1/100s	TSSOP10, DFN2626-10
PCF85363A	X	2	I <sup>2</sup> C	230	X	X	-	time stamp, battery backup, stopwatch 1/100s, 64 Byte RAM	TSSOP10, TSSOP8, DFN2626-10
PCF85363B	X	2	SPI	230	X	X	-	time stamp, battery backup, stopwatch 1/100s, 64 Byte RAM	TSSOP10, DFN2626-10
PCF2123	X	1	SPI	100	-	-	-	lowest power 100 nA in operation	TSSOP14, HVQFN16
PCF8523	X	2	I <sup>2</sup> C	150	X	-	-	lowest power 150 nA in operation, FM+ 1 MHz	SO8, HVSON8, TSSOP14, WLCSP
PCF8563	X	1	I <sup>2</sup> C	250	-	-	-	-	SO8, TSSOP8, HVSON10
PCA8565	X	1	I <sup>2</sup> C	600	-	-	grade 1	high robustness, T <sub>amb</sub> = -40 °C to 125 °C	TSSOP8, HVSON10
PCA8565A	X	1	I <sup>2</sup> C	600	-	-	-	integrated oscillator caps, T <sub>amb</sub> = -40 °C to 125 °C	WLCSP
PCF8564A	X	1	I <sup>2</sup> C	250	-	-	-	integrated oscillator caps	WLCSP

Table 35. Selection of Real-Time Clocks ...continued

Type name	Alarm, Timer, Watchdog	Interrupt output	Interface	I <sub>DD</sub> , typical (nA)	Battery backup	Timestamp, tamper input	AEC-Q100 compliant	Special features	Packages
PCF2127	X	1	I <sup>2</sup> C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated, 512 Byte RAM	SO16
PCF2127A	X	1	I <sup>2</sup> C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated, 512 Byte RAM	SO20
PCF2129	X	1	I <sup>2</sup> C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated	SO16
PCF2129A	X	1	I <sup>2</sup> C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated	SO20
PCA2129	X	1	I <sup>2</sup> C and SPI	500	X	X	grade 3	temperature compensated, quartz built in, calibrated	SO16
PCA21125	X	1	SPI	820	-	-	grade 1	high robustness, T <sub>amb</sub> = -40 °C to 125 °C	TSSOP14

## 21. Abbreviations

**Table 36. Abbreviations**

Acronym	Description
BCD	Binary Coded Decimal
CMOS	Complementary Metal Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
I <sup>2</sup> C	Inter-Integrated Circuit
IC	Integrated Circuit
LSB	Least Significant Bit
MSB	Most Significant Bit
MSL	Moisture Sensitivity Level
PCB	Printed-Circuit Board
POR	Power-On Reset
RTC	Real-Time Clock
SCL	Serial CLock line
SDA	Serial DATa line
SMD	Surface Mount Device

## 22. References

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- [1] **AN10365** — Surface mount reflow soldering description
- [2] **AN10366** — HVQFN application information
- [3] **AN11247** — Improved timekeeping accuracy with PCF85063, PCF8523 and PCF2123 using an external temperature sensor
- [4] **IEC 60134** — Rating systems for electronic tubes and valves and analogous semiconductor devices
- [5] **IEC 61340-5** — Protection of electronic devices from electrostatic phenomena
- [6] **IPC/JEDEC J-STD-020** — Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices
- [7] **JESD22-A114** — Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)
- [8] **JESD22-C101** — Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components
- [9] **JESD78** — IC Latch-Up Test
- [10] **JESD625-A** — Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices
- [11] **SOT1069-2\_147** — HWSO8; Reel pack, SMD, 7", packing information
- [12] **UM10204** — I<sup>2</sup>C-bus specification and user manual
- [13] **UM10301** — User Manual for NXP Real Time Clocks PCF85x3, PCA8565 and PCF2123, PCA2125
- [14] **UM10569** — Store and transport requirements
- [15] **UM10698** — User manual for I2C-bus RTC demo board OM11059A

## 23. Revision history

Table 37. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCF85063TP v.4	20150506	Product data sheet	-	PCF85063TP v.3
Modifications:	<ul style="list-style-type: none"><li>• Corrected rise and fall time specification according to the I<sup>2</sup>C standard, see <a href="#">Table 32</a></li><li>• Adjusted <a href="#">Section 8.2.3</a></li><li>• Enhanced <a href="#">Section 8.2.2.1</a></li></ul>			
PCF85063TP v.3	20130711	Product data sheet	-	PCF85063TP v.2
PCF85063TP v.2	20130415	Product data sheet	-	PCF85063TP v.1
PCF85063TP v.1	20130122	Objective data sheet	-	-

## 24. Legal information

### 24.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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